

Impact Of The Effective Conducting Path Effect (ECPE) On The Convergence Of The Evanescent And The Polynomial Models: Applied To The Submicronic MOSFET

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Abstract: We present a comparative study of submicronic MOSFET characteristics using analytic models of electrostatic potential in the channel. We are particularly interested in the surface potential, threshold voltage, swing and DIBL using the polynomial model with and without ECPE and the evanescent model to analytically express the electrostatic potential. The results show a good agreement between the polynomial model including ECPE, the evanescent model and measures done by simulation tools.

Keywords: submicronic MOSFET; evanescent model; effective conducting path effect; DIBL and Swing.

I. Introduction

The CMOS technology with very large scale integrated (VLSI), due to its technological simplicity and its low cost, remains the principal technology of the Ultra-submicronic components functioning with low supplying tensions. The components miniaturization, generating unsatisfactory performances, has led searchers to figure out eventual possibilities to reduce short channel effects on the components performances [1-2]. The characteristic length λ , defined through the resolution of the 2D Poisson equation and relying on the transistor geometric parameters [3], represents one of the parameters characterizing the short channel effects. The decreasing of the characteristic length λ , through the MOSFET geometry changing such as SSR-MOSFET, DG-MOSFET and CG-MOSFET [3-4], has improved its performances.

In this paper, we develop the evanescent model to determine the surface potential, the threshold voltage, the DIBL and Swing for the submicronic MOSFET transistor. We compare these results with those obtained from the polynomial model of electrostatic potential with and without ECPE [5] and simulation measures [6-7-8-9].

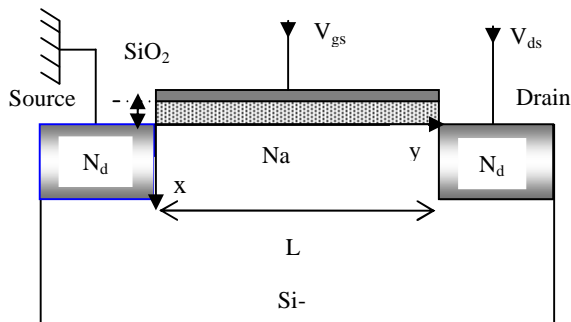


Figure1: Conventional MOSFET

II. Evanescent model

II-1. Surface potential and threshold voltage

The surface potential and the threshold voltage are deduced through the 2D Poisson equation neglecting beforehand the inversion charge in regard to that of the depletion. We define the channel length by L , the homogenous doping below the grid by N_a and the silicon permittivity by ϵ_{si} .

In the evanescent model, the electrostatic potential is represented by $\varphi(x,y) = \varphi_1(x) + \varphi_2(x,y)$. $\varphi_1(x)$ is the solution of Poisson equation for a long channel and $\varphi_2(x,y)$ is the solution of the Laplace equation and contain the short channel effect.

$$\frac{d^2\varphi(x,y)}{dx^2} + \frac{d^2\varphi(x,y)}{dy^2} = \frac{qN_a}{\epsilon_{si}} \quad (1)$$

The necessary boundary conditions of φ_1 and φ_2 to define $\varphi(x)$ are as follow:

For φ_1 :

$$\varphi_1(x=0) = V_{SL} = \varphi_{gf} - \frac{qN_a T_{ox} x_m}{\epsilon_{ox}}$$

$$-\frac{\partial \varphi_1}{\partial x} \Big|_{x=0} = \frac{C_{ox}}{\epsilon_{si}} (\varphi_1(0) - \varphi_{gf}) \quad \text{where } \varphi_{gf} = V_{GS} - V_{FB}$$

V_{SL} represents the surface potential for a long channel, V_{GS} is the grid bias and V_{FB} is the flat band voltage.

$x_m = \left[\frac{2\epsilon_{si}(2\phi_B - V_{BS})}{qN_a} \right]^{\frac{1}{2}}$ is the maximum depletion

region in the channel, $\phi_B = \frac{KT}{q} \ln \left(\frac{N_a}{n_i} \right)$ is the

Fermi potential in the channel and $C_{ox} = \left(\frac{\epsilon_{ox}}{T_{ox}} \right)$ is the capacity of the grid oxide per surface unity.

For φ_2 :

$$\begin{cases} \varphi_2(x, y=0) = V_{bi} - \varphi_1(x) \\ \varphi_2(x, y=L) = V_{bi} + V_{ds} - \varphi_1(x) \end{cases} \quad \begin{cases} \left(\frac{\partial \varphi_2}{\partial x}\right)_{x=0} = \frac{C_{ox}}{\epsilon_{si}} \varphi_2(x=0, y) \\ \left(\frac{\partial \varphi_2}{\partial x}\right)_{x=L} = 0 \end{cases}$$

where $V_{bi} = \frac{kT}{q} \ln\left(\frac{N_a \cdot N_d}{n_i^2}\right)$ denotes the built-in voltage

between the source/drain end, with the doping N_d , and silicon body and V_{ds} is the drain bias. T_{ox} is the oxide thickness.

$\varphi_s(y) = \varphi_1(0) + \varphi_2(0, y)$ is the surface potential of silicon ($x=0$) and write explicitly as follow:

$$\varphi_s(y) = V_{SL} + \left\{ (V_{bi} + V_{ds} - V_{SL}) \cdot \frac{\sinh(y/\lambda_e)}{\sinh(L/\lambda_e)} + (V_{bi} - V_{SL}) \cdot \frac{\sinh((L-y)/\lambda_e)}{\sinh(L/\lambda_e)} \right\}. \quad (2)$$

λ_e is the characteristic length of the evanescent model and verify the follow equality

$$\tan g\left(\frac{x_m}{\lambda_e}\right) - \frac{C_{ox}}{\epsilon_{si}} \lambda_e = 0. \quad (3)$$

Threshold voltage is defined as a grid voltage ($V_{GS} = V_{th}$) for $\varphi_s = 2\phi_B$. This leads to write V_{th} as follow:

$$V_{th} - V_{FB} = \frac{qN_a}{C_{ox}} x_{max} + \left\{ 2\phi_B - (V_{bi} + V_{ds}) \cdot \frac{\sinh(y/\lambda_e)}{\sinh(L/\lambda_e)} - V_{bi} \cdot \frac{\sinh((L-y)/\lambda_e)}{\sinh(L/\lambda_e)} \right\} \cdot \left[1 - \frac{\sinh(y/\lambda_e)}{\sinh(L/\lambda_e)} - \frac{\sinh((L-y)/\lambda_e)}{\sinh(L/\lambda_e)} \right]. \quad (4)$$

The gradient of threshold voltage is defined as

$$\Delta V_{th} = V_{th0} - V_{th} \text{ where } V_{th0} - V_{FB} = \frac{qN_a}{C_{ox}} x_{max} + 2\phi_B \text{ and } V_{th0}$$

denote the threshold voltage for a long channel MOSFET [8].

II-2. DIBL

In the MOSFET structures with short channel, the surface potential minimum increase with the drain voltage. Thus, the short channel effect is attributed to the penetration of the electric field line, of the drain-channel junction, in the channel resulting in the potential barrier lowering (DIBL). This leads to the decreasing of the threshold voltage.

The \mathfrak{R} parameter defined by $\mathfrak{R} = \frac{\partial V_{th}}{\partial V_{ds}}$ evaluates the

DIBL effect and written as

$$\mathfrak{R} = \frac{2\sinh^2(L/2\lambda_e)}{K_1} \left\{ -1 + \frac{K_2}{(K_2^2 - K_1 K_3)^{1/2}} \right\} + \frac{V_{ds}}{(K_2^2 - K_1 K_3)^{1/2}}. \quad (5)$$

where

$$K_1 = \sinh^2(L/\lambda_e) - 4\sinh^2(L/2\lambda_e)$$

$$K_2 = (2\phi_B - V_{bi}) \sinh^2(L/\lambda_e) - 2V_{ds} \sinh^2(L/2\lambda_e)$$

$$K_3 = (2\phi_B - V_{bi})^2 \sinh^2(L/\lambda_e) + V_{ds}^2$$

II-3. Swing

The subthreshold slope parameter, appealed Swing, is defined as the grid voltage that modifies the drain current under a threshold of a decade and written as

$$S = \frac{\partial V_{gs}}{\partial \ln(I_{ds})} \text{ where } I_{ds} \text{ denotes the drain current.}$$

Sean be written differently according to the minimum surface potential

$$\varphi_{smin} : S = \ln(10) \cdot \frac{\partial V_{gs}}{\partial \varphi_{smin}} \cdot \frac{\partial \varphi_{smin}}{\partial \ln(I_{ds})}. \text{ When the surface}$$

states are neglected, the drain current is proportional to

$$\exp\left(\frac{q\varphi_{smin}}{KT}\right). \text{ This leads to write } S \text{ as follows}$$

$$S = \frac{kT}{q} \ln(10) \cdot \frac{\partial V_{gs}}{\partial \varphi_{smin}}.$$

The determination of the minimum surface potential y_0 abscise allows to write the parameter S taking into consideration the short channel effect as

$$S = \frac{KT}{q} \ln(10) \cdot \frac{\partial V_{gs}}{\partial V_{SL}} \cdot \left(1 - \frac{\sinh(y_0/\lambda_e)}{\sinh(L/\lambda_e)} - \frac{\sinh((L-y_0)/\lambda_e)}{\sinh(L/\lambda_e)} \right)^{-1}$$

. (6)

The corrective term

$$\gamma_s = \left(1 - \frac{\sinh(y_0/\lambda_e)}{\sinh(L/\lambda_e)} - \frac{\sinh((L-y_0)/\lambda_e)}{\sinh(L/\lambda_e)} \right) \quad (7)$$

denotes the short channel effect [10].

$$\frac{\partial V_{gs}}{\partial V_{SL}} = 1 + \frac{C_{dep}}{C_{ox}} \quad (8)$$

illustrates undoubtedly the modulation of the surface potential for a long channel MOSFET caused by the grid bias.

Finally, the swing can be written as

$$S = \frac{KT}{q} \cdot \log_{10} \cdot \frac{1}{\gamma_s} \cdot \left(1 + \frac{C_{dep}}{C_{ox}} \right). \quad (9)$$

where $C_{dep} = \frac{x_{max}}{\epsilon_{si}}$ denote the capacity of the depletion

region in the channel.

III. Effective Conduction Path Effect

Considering the polynomial model [11] that consider the conduction current is at the surface of the silicon body and supposes parabolically the electrostatic potential profile in the

$$\varphi(x, y) = C_0(y) + C_1(y)x + C_2(y)x^2. \quad (10)$$

vertical direction. Using the classical boundary conditions [12]

$$\begin{cases} \varphi(x, y=0) = V_{bi} \\ \varphi(x, y=L) = V_{bi} + V_{ds} \end{cases} \quad \begin{cases} \left. \frac{\partial \varphi}{\partial x} \right|_{x=0} = \frac{C_{ox}}{\epsilon_{si}} (\varphi(0, y) - \varphi_{gf}) \\ \left. \frac{\partial \varphi}{\partial x} \right|_{x=x_m} = 0 \end{cases}$$

and writing the Poisson equation as $\varphi_s(x, y)$, we deduce the polynomial characteristic length

$$\lambda_p = (\epsilon_{si} x_{max} / C_{ox})^{1/2}. \quad (11)$$

The notion of the ECPE supposes that the gravity center of the conduction current is at $x = d_{eff}$. The presentation of the electrostatic potential $\varphi(x, y)$ at $x = d_{eff}$ allows us to bring about a correction to polynomial characteristic length λ_p . The new corrected characteristic length corresponding to the polynomial model including ECPE is

$$\lambda_{pc} = \lambda_p \left(1 + \frac{C_{ox} d_{eff}}{\epsilon_{si}} - 1/2 \frac{C_{ox} d_{eff}^2}{\epsilon_{si} x_m} \right)^{1/2} \quad (12)$$

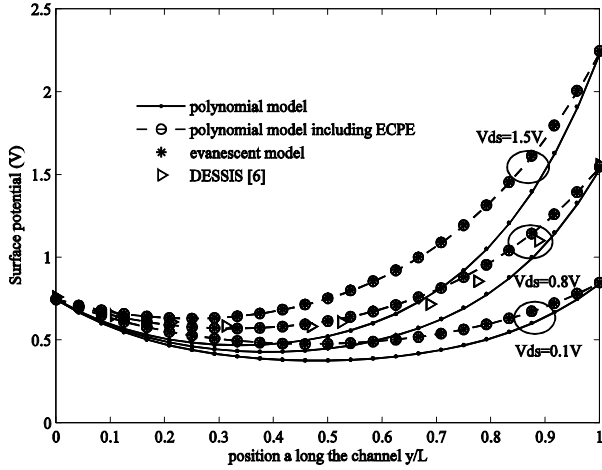


Figure 2. Surface potential versus normalized position a channel length y/L

The evanescent model and the polynomial model with and without the ECPE are utilized to analysis the short channel effect. The analytic expressions of $\varphi_s, V_{th}, \Delta V_{th}, \mathcal{R}$ et S presented through the evanescent model remain adequate for the polynomial models with and without ECPE save for the characteristic length $\lambda_{i=e,p,pc}$ which changes in the expressions.

IV. Results and Discussion

We have looked through the convergence of the models studying the short channel effect. The analytic expressions of $\varphi_s, V_{th}, \Delta V_{th}, \mathcal{R}$ and S are analysis using the models mentioned above. To prove the convergence of the models, some measure of simulators are superposed to the figures of the parameters above.

For the three models, the figure 2 shows the evolution of the surface potential along with the normalized position of the channel length for $N_a = 6.10^{17} \text{cm}^{-3}$, $T_{ox} = 3.5 \text{nm}$, $L = 80 \text{nm}$ and $V_{ds} = 0.1, 0.8$ et 1.5V . We notice that the convergence of the evanescent model and polynomial model including ECPE in a large of scale the drain bias at $d_{eff} = 0.5T_{ox}$. A good agreement, for $V_{ds} = 0.8 \text{V}$, has been observed between these models and measures of the simulator DESSIS [7].

Figure 3 presents the evolution of the gradient of threshold voltage in regard to the normalized position of the channel length for $N_a = 1.5.10^{18} \text{cm}^{-3}$, $V_{ds} = 1 \text{V}$, $L = 500 \text{nm}$ and $T_{ox} = 1.5 \text{nm}$ and for $N_a = 3.10^{17} \text{cm}^{-3}$, $V_{ds} = 1 \text{V}$, $L = 500 \text{nm}$ and $T_{ox} = 5 \text{nm}$.

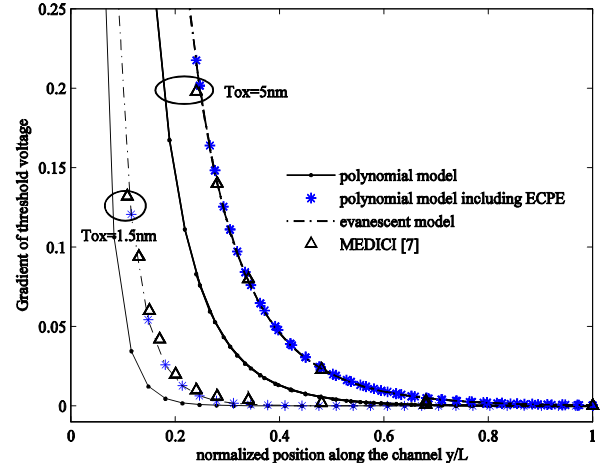


Figure 3. Variation of gradient of threshold voltage versus normalized position along the channel y/L

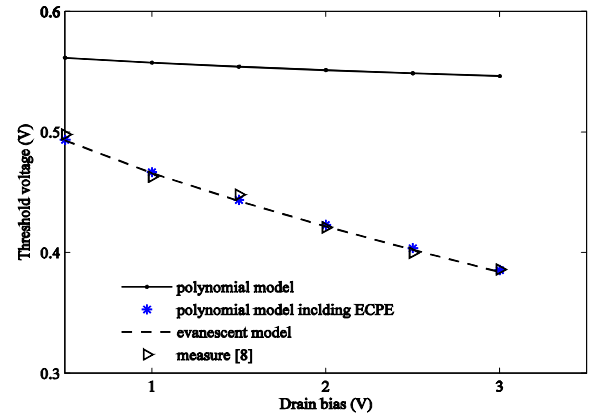


Figure 4. Variation of threshold voltage versus drain bias

We see a good agreement, at $d_{eff} = 0.5T_{ox}$, a between the evanescent model, the polynomial model including ECPE and the measures of the simulator MEDICI [6].

The study of the threshold voltage in regard to the drain bias (V_{ds}) presented in figure 4, displays a good convergence, at $d_{eff} = 0.5T_{ox}$, of the evanescent model, the polynomial model including ECPE and some measure of the reference [8] for $N_a = 3.6.10^{17} \text{cm}^{-3}$, $T_{ox} = 5.5 \text{nm}$ and $L = 0.3 \mu\text{m}$. The evolutions are almost linear as stated by the model DIBL [13].

The evolution R is reported in figure 5 (for $N_a=3.10^{17}\text{cm}^{-3}$, $T_{ox}=5.5\text{nm}$, $L=0.5\mu\text{m}$ and $V_{ds}=0.5\text{V}$) for the three models. A good convergence, at $d_{eff} = 0.5T_{ox}$, has been noticed, along the channel, for the evanescent model and the polynomial model including ECPE.

Figure 6 illustrates the evolution of the parameter S in regard to the channel length for $N_a=1.10^{17}\text{cm}^{-3}$, $T_{ox}=10\text{nm}$ and $V_{ds}=0.1\text{V}$. The evanescent and the polynomial including ECPE models presents, at $d_{eff} = 0.5T_{ox}$, a good agreement and a little disagreement between these models and the measures of simulator MEDICI [9]. The study of some parameters show a little disagreement between the polynomial model without the ECPE and the others.

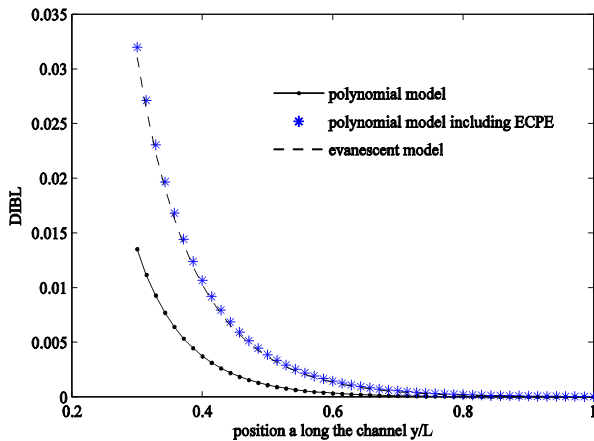


Figure 5. DIBL versus normalized position a channel length y/L

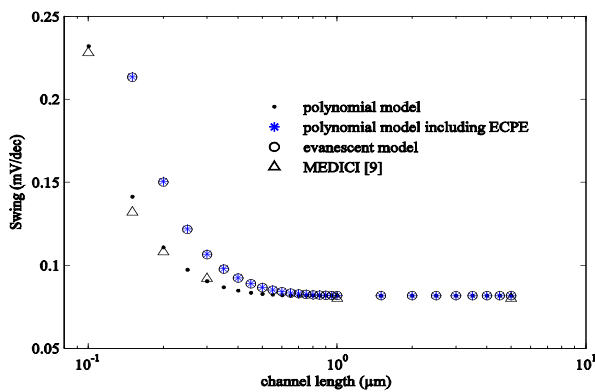


Figure 6. Subthreshold Swing versus a channel length L

V. Conclusion

The short channel effects studied through the surface potential, threshold voltage, DIBL and swing show a good convergence between the evanescent model and the polynomial model including ECPE at $d_{eff} = 0.5T_{ox}$. This agreement of these analytic models is proved by different of 2D simulator.

VI. References

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